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LPKF Introduces New Laser for Depaneling

June 2010, Tualatin, OR – Another laser system by LPKF is taking the stage. The **MicroLine 1000 S** presents a compact and cost-effective method for UV-laser depaneling of thin-rigid and rigid-flex assembled PCBs. Dr. Ingo Bretthauer, Chairman of the LPKF Board of Directors stated: “The **MicroLine 1000 S** combines a low entry level price with the highest cutting quality and superior process capabilities. At the same time it is especially flexible and therefore suited for high manufacturing variance. We are using a laser source which was optimized just for this application”.

With UV-laser cutting of assembled and/or unassembled PCBs those offering limited space will benefit. The UV laser beam can cut right along delicate components or circuit paths without mechanical or thermal interference. The tool-less method makes any contour a possibility. Changes to the cutting paths are made through programming the software included with the machine, or right in the CAD software.

About LPKF

LPKF Laser & Electronics AG manufactures machines and laser systems used in electronics fabrication, the automotive sector, and the production of solar cells. Around 20 percent of the workforce is engaged in research and development.



<http://www.lpkfusa.com/images/ML1000S.jpg>

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